

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	N/A	Silicon Carbide (SiC)	409-21-2	0.03186	100.0	0.64
Subtotal				0.03186	100	0.64
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02197	100.0	0.44134
Subtotal				0.02197	100	0.44134
Solder Wire	Lead alloy	Tin (Sn)	7440-31-5	0.00054	2.0	0.0108
	Lead alloy	Silver (Ag)	7440-22-4	0.00067	2.5	0.0135
	Lead alloy	Lead (Pb)	7439-92-1	0.02567	95.5	0.5157
Subtotal				0.02688	100	0.54
Post-plating	Lead alloy	Tin (Sn)	7440-31-5	0.74678	100.0	15
Subtotal				0.74678	100	15
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02116	0.03	0.4251
	Copper alloy	Iron (Fe)	7439-89-6	0.07055	0.1	1.417
	Copper alloy	Copper (Cu)	7440-50-8	70.3131	99.67	1,412.3239
	Copper alloy	Silver (Ag)	7440-22-4	0.14109	0.2	2.834
Subtotal				70.5459	100	NaN
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.86073	6.5	37.375
	Polymer	Epichlorohydrin/o-Cresol/Formaldehyde polymer (generic)	29690-82-2	4.58026	16.0	92
	Filler	Silica fused	60676-86-0	20.32489	71.0	408.25
	Flame retardant	Metal hydroxide		1.86073	6.5	37.375
Subtotal				28.62661	100	575
Total				100	100	NaN

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.